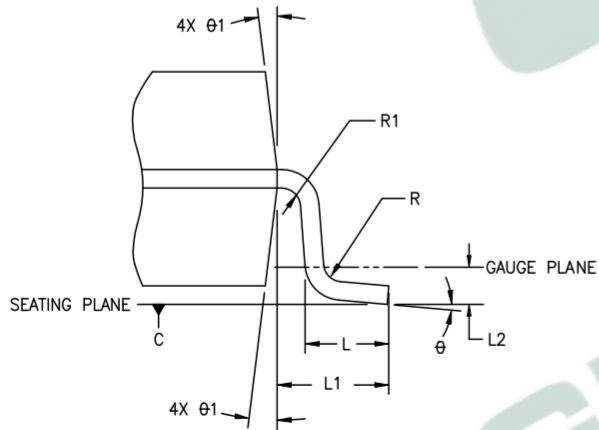


TOP VIEW

SIDE VIEW



SYMBOL	MIN	NOM	MAX
A	--	--	1.35
A1	0	--	0.15
A2	1.0	1.1	1.2
b	0.35	--	0.45
D	2.82	2.92	3.02
E	2.60	2.80	3.00
E1	1.526	1.626	1.726
e	0.9	0.95	1.0
L	0.35	0.45	0.6
L1	0.6REF		
L2	0.25REF		
R	0.1	--	--
R1	0.1	--	0.25
$\theta$	0°	4°	8°
$\theta 1$	5°	10°	15°

NOTES:

1. ALL DIMENSIONS REFER TO JEDEC STANDARD MO-178
2. DIMENSION D DOES NOT INCLUDE MOLD FLASH
3. DIMENSION E1 DOES NOT INCLUDE MOLD FLASH
4. FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.



上海季丰电子科技有限公司

GIGA FORCE ELECTRONICS CO., Limited

制图	王磊	Title	Package Outline SOT23-6	
核准	何桂港	POD No	POD-SHJF-42	
日期	2022. 3. 31	DIMENSIONS IN:	mm	Rev:A